

1A Surface Mount Glass Passivated Bridge Rectifier

Features

- Glass Passivated Chip Junction
- Reverse Voltage - 100 to 1000 V
- Forward Current - 1 A
- High Surge Current Capability
- Designed for Surface Mount Application



Mechanical Data

- Case: MBF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 75mg 0.0026oz

Maximum Ratings and Electrical Characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	LTM1F-10	LTM2F-10	LTM4F-10	LTM6F-10	LTM8F-10	LTM10F-10	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	100	200	400	600	800	1000	V
Average Rectified Output Current at $T_c = 125\text{ }^\circ\text{C}$	I_O	1.0						A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	35						A
Maximum Forward Voltage at 1.0 A	V_F	1.1						V
Maximum DC Reverse Current at Rated DC Blocking Voltage	I_R	@ $T_A = 25\text{ }^\circ\text{C}$ 5						μA
		@ $T_A = 125\text{ }^\circ\text{C}$ 40						
Typical Junction Capacitance (Note1)	C_j	13						pF
Typical Thermal Resistance (Note2)	$R_{\theta JA}$ $R_{\theta JC}$	80						$^\circ\text{C/W}$
		25						
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150						$^\circ\text{C}$

Note: 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.

2. Mounted on glass epoxy PC board with 4×1.5"×1.5" (3.81×3.81 cm) copper pad.

Ratings and characteristics Curves

Fig.1 Average Rectified Output Current Derating Curve

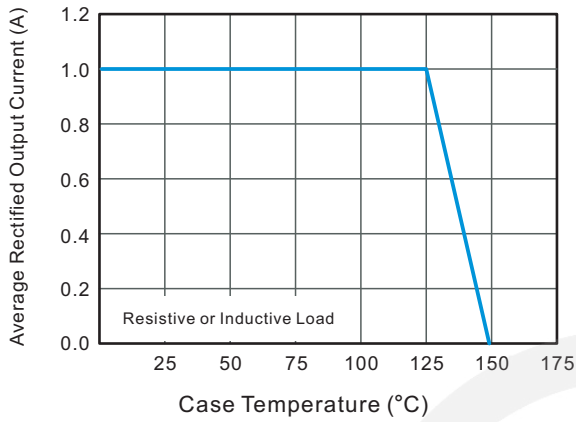


Fig.2 Typical Reverse Characteristics

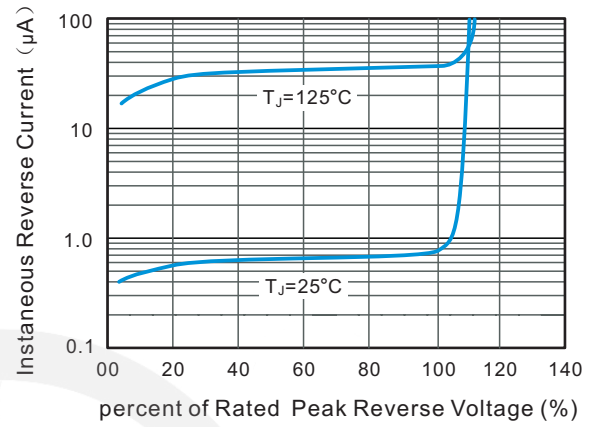


Fig.3 Typical Instantaneous Forward Characteristics

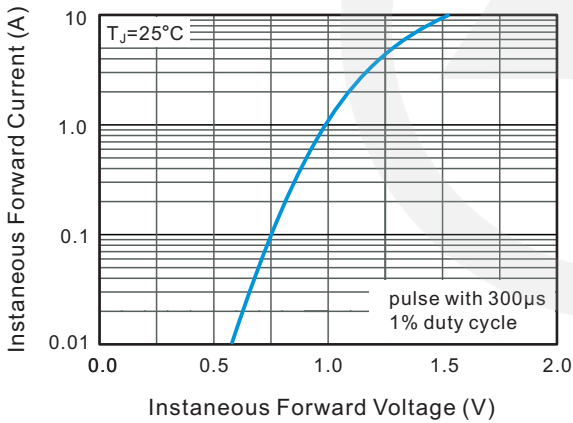


Fig.4 Typical Junction Capacitance

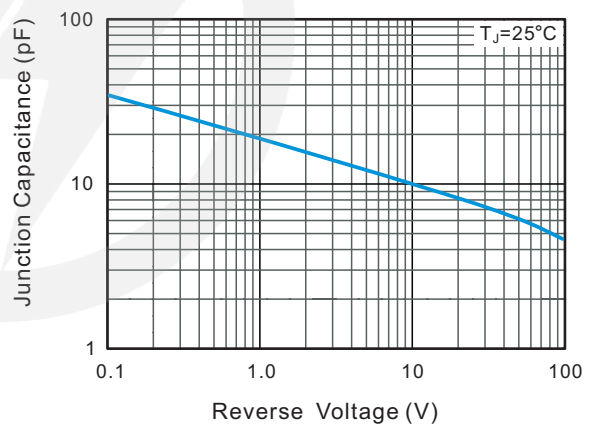
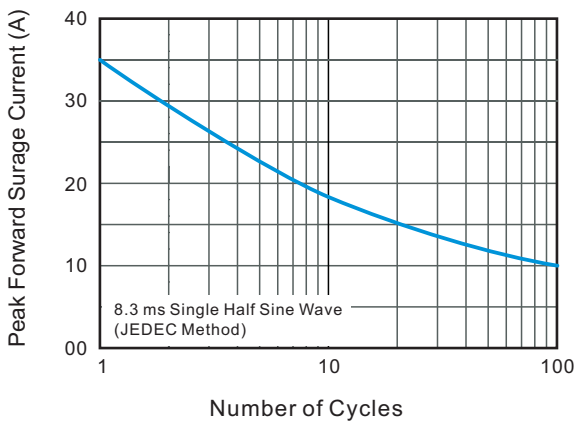
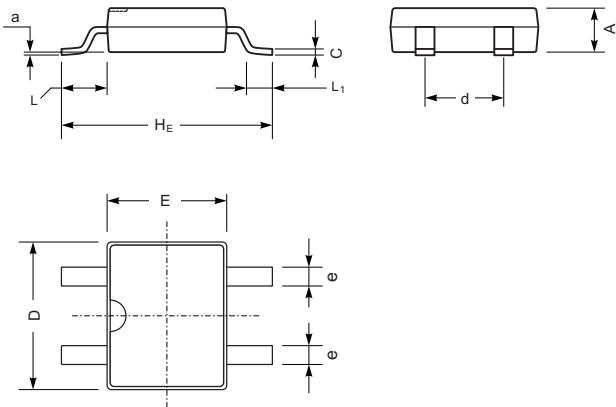


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current



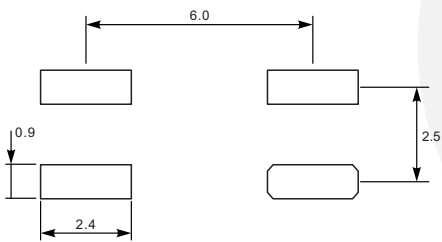
MBF Package Outline



Unit: mm

SYMBOL	DIMENSIONS	
	MIN.	MAX.
A	1.20	1.60
C	0.15	0.22
D	4.50	5.00
E	3.60	4.10
HE	6.40	7.00
d	2.30	2.70
e	0.50	0.80
L	1.30	1.70
L1	0.50	1.10
a	0.20 MAX.	

MBF Suggested Pad Layout

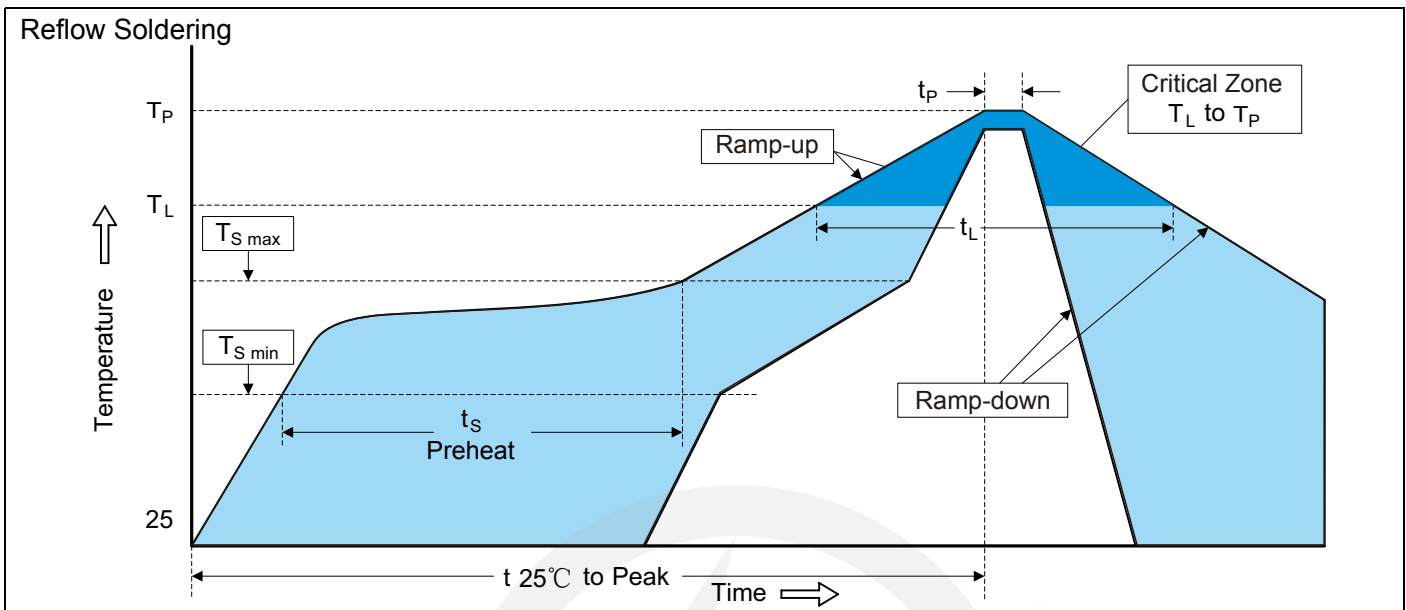


- Note:
1. Controlling dimension: in millimeters.
 2. General tolerance: $\pm 0.05\text{mm}$
 3. The pad layout is for reference purpose only.

Marking

Type number	Marking code
LTM1F-10	MB1F
LTM2F-10	MB2F
LTM4F-10	MB4F
LTM6F-10	MB6F
LTM8F-10	MB8F
LTM10F-10	MB10F

Recommended Soldering Conditions



Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	3°C/second max.
Preheat -Temperature Min ($T_{S\ min}$) -Temperature Max ($T_{S\ max}$) -Time (min to max) (t_s)	150°C 200°C 60-180 seconds
$T_{S\ max}$ to T_L -Ramp-up Rate	3°C/second max.
Time maintained above: -Temperature (T_L) -Time (t_L)	217°C 60-150 seconds
Peak Temperature (T_P)	260°C
Time within 5°C of actual Peak Temperature (t_P)	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

Packaging

13" Reel



D5 $\Phi 330.0 \pm 2.0$

D6 $\Phi 13.5 \pm 0.5$

H 2.5 ± 1.0

W2 16.0 ± 2.0

Quantity: 5000PCS